|  | LDM8002A-M621<br>CE MOUNT SILICON<br>P-CHANNEL   |  | w                    | ww.centralsemi.com          |  |
|--|--|--|----------------------|-----------------------------|--|
| ENH  | ANCEMENT-MODE  | DESCRIPTI<br>The CENTR   |                      | R CTLDM8002A-M621           |  |
|  | MOSFET   | is a silicon F   | P-Channel enhancem   | ent-mode MOSFET in          |  |
|  |  | a small, ther  | mally efficient, TLM | <sup>™</sup> 2x1mm package. |  |
| TLM  |  | MARKING (  | CODE: CN             |                             |  |
| · ·  | Top View Bottom View   | FEATURES   | :                    |                             |  |
|  | TLM621 CASE  | • Low rDS(on)  |                      |                             |  |
|  |  | Low V <sub>DS(or</sub>   |                      |                             |  |
| APPLICATIO   |  | Low Thresho  |                      |                             |  |
| Load/Power Strendy   | witches<br>Converter Circuits  | Fast Switching   |                      |                             |  |
|  | ed Portable Equipment  | <ul> <li>Logic Level Compatible</li> <li>Small TLM™ 2x1mm Package</li> </ul> |                      |                             |  |
|  |  | SYMBOL   |                      |                             |  |
| Drain-Source Vo  | TINGS: (T <sub>A</sub> =25°C)  | V <sub>DS</sub>  | 50                   | UNITS<br>V                  |  |
| Drain-Gate Volta   | 0  | V <sub>DG</sub>  | 50                   | V                           |  |
| Gate-Source Vo   | 0  | V <sub>GS</sub>  | 20                   | V                           |  |
| Continuous Dra   | 0  | I <sub>D</sub>   | 280                  | mA                          |  |
| Continuous Source Current (Body Diode)                                   |  | IS   | 280                  | mA                          |  |
| Maximum Pulse  | d Drain Current  | IDM  | 1.5                  | А                           |  |
| Maximum Pulsed Source Current  |  | ISM  | 1.5                  | А                           |  |
| Power Dissipation (Note 1)<br>Operating and Storage Junction Temperature |  | PD   | 0.9                  | W                           |  |
|  |  | T <sub>J,</sub> T <sub>stg</sub>   | -65 to +150          | °C                          |  |
| Thermal Resista  | ance (Note 1)  | $\Theta_{JA}$  | 139                  | °C/W                        |  |
| ELECTRICAL C   | CHARACTERISTICS: (T <sub>A</sub> =25°C un  | lless otherwise r  | noted)               |                             |  |
| SYMBOL   | TEST CONDITIONS  | MIN  | MAX                  | UNITS                       |  |
| IGSSF, IGSSR   |  |  | 100                  | nA                          |  |
| IDSS   | V <sub>DS</sub> =50V, V <sub>GS</sub> =0   |  | 1.0                  | μΑ                          |  |
| IDSS   | V <sub>DS</sub> =50V, V <sub>GS</sub> =0, T <sub>J</sub> =125°C                          | 500  | 500                  | μA                          |  |
| ID(ON)   | V <sub>GS</sub> =10V, V <sub>DS</sub> =10V   | 500  |                      | mA                          |  |
| BVDSS  | $V_{GS}=0, I_D=10\mu A$  | 50   | 0.5                  | V                           |  |
| V <sub>GS</sub> (th)   | $V_{DS}=V_{GS}$ , $I_{D}=250\mu$ A   | 1.0  | 2.5                  | V                           |  |
| VDS(ON)  | V <sub>GS</sub> =10V, I <sub>D</sub> =500mA  |  | 1.5                  | V<br>V                      |  |
| VDS(ON)  | V <sub>GS</sub> =5.0V, I <sub>D</sub> =50mA  |  | 0.15<br>1.3          | V<br>V                      |  |
| V <sub>SD</sub>  | V <sub>GS</sub> =0, I <sub>S</sub> =115mA<br>V <sub>GS</sub> =10V, I <sub>D</sub> =500mA |  | 2.5                  | ν                           |  |
| rDS(ON)  | V <sub>GS</sub> =10V, I <sub>D</sub> =500mA, T <sub>J</sub> =125°(                       | 2  | 4.0                  | Ω                           |  |
| <sup>r</sup> DS(ON)  | V <sub>GS</sub> =5.0V, I <sub>D</sub> =50mA  | -  | 3.0                  | Ω                           |  |
| <sup>r</sup> DS(ON)<br><sup>r</sup> DS(ON)                               | V <sub>GS</sub> =5.0V, I <sub>D</sub> =50mA, T <sub>J</sub> =125°C                       |  | 5.0                  | Ω                           |  |
| 9FS  | V <sub>DS</sub> =10V, I <sub>D</sub> =200mA  | 200  | 0.0                  | mS                          |  |
| ers<br>C <sub>rss</sub>  | V <sub>DS</sub> =25V, V <sub>GS</sub> =0, f=1.0MHz                                       |  | 7.0                  | pF                          |  |
| C <sub>iss</sub>   | V <sub>DS</sub> =25V, V <sub>GS</sub> =0, f=1.0MHz                                       |  | 70                   | pF                          |  |
| C <sub>OSS</sub>   | V <sub>DS</sub> =25V, V <sub>GS</sub> =0, f=1.0MHz                                       |  | 15                   | pF                          |  |
|  | PCB with copper mounting pad area of 33mm  | 1 <sup>2</sup> .   |                      | R2 (6-February 2015)        |  |

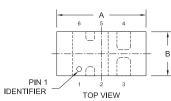


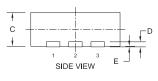
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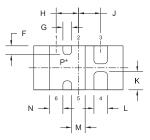
## SURFACE MOUNT SILICON P-CHANNEL ENHANCEMENT-MODE MOSFET

| ELECTRICAL CHARACTERISTICS - Continued: (T <sub>A</sub> =25°C unless otherwise noted) |  |      |     |       |  |  |  |  |
|---|--|------|-----|-------|--|--|--|--|
| SYMBOL  | TEST CONDITIONS  | TYP  | MAX | UNITS |  |  |  |  |
| Q <sub>g(tot)</sub>   | V <sub>DS</sub> =25V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =100mA | 0.72 |     | nC    |  |  |  |  |
| Qgs   | V <sub>DS</sub> =25V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =100mA | 0.25 |     | nC    |  |  |  |  |
| Q <sub>gd</sub>   | $V_{DS}$ =25V, $V_{GS}$ =4.5V, $I_{D}$ =100mA                      | 0.16 |     | nC    |  |  |  |  |
| ton, toff   | V <sub>DD</sub> =30V, V <sub>GS</sub> =10V, I <sub>D</sub> =200mA, |      |     |       |  |  |  |  |
|   | R <sub>G</sub> =25Ω, R <sub>L</sub> =150Ω                          |      | 20  | ns    |  |  |  |  |

## **TLM621 CASE - MECHANICAL OUTLINE**

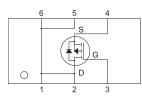






R2 BOTTOM VIEW \*Exposed pad P connects pins 1, 2, 5, and 6

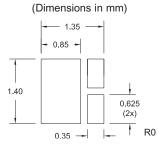
### **PIN CONFIGURATION**



| DIMENSIONS       |        |       |             |       |  |  |  |
|------------------|--------|-------|-------------|-------|--|--|--|
| SYMBOL           | INCHES |       | MILLIMETERS |       |  |  |  |
| STNDUL           | MIN    | MAX   | MIN         | MAX   |  |  |  |
| А                | 0.073  | 0.085 | 1.850       | 2.150 |  |  |  |
| В                | 0.033  | 0.045 | 0.850       | 1.150 |  |  |  |
| С                | 0.028  | 0.031 | 0.700       | 0.800 |  |  |  |
| D                | 0.006  |       | 0.150       |       |  |  |  |
| E                | 0.000  | 0.002 | 0.000       | 0.050 |  |  |  |
| F                | 0.008  |       | 0.200       |       |  |  |  |
| G                | 0.010  |       | 0.250       |       |  |  |  |
| Н                | 0.020  |       | 0.500       |       |  |  |  |
| J                | 0.020  |       | 0.500       |       |  |  |  |
| К                | 0.012  | 0.020 | 0.300       | 0.500 |  |  |  |
| L                | 0.007  | 0.012 | 0.180       | 0.300 |  |  |  |
| М                | 0.007  | 0.012 | 0.180       | 0.300 |  |  |  |
| Ν                | 0.007  | 0.012 | 0.180       | 0.300 |  |  |  |
| TLM621 (REV: R2) |        |       |             |       |  |  |  |

TLM621 (REV: R2)

## SUGGESTED MOUNTING PADS



# LEAD CODE:

- 1) Drain 2) Drain 3) Gate
- 4) Source
- 5) Drain
- 6) Drain

# MARKING CODE: CN

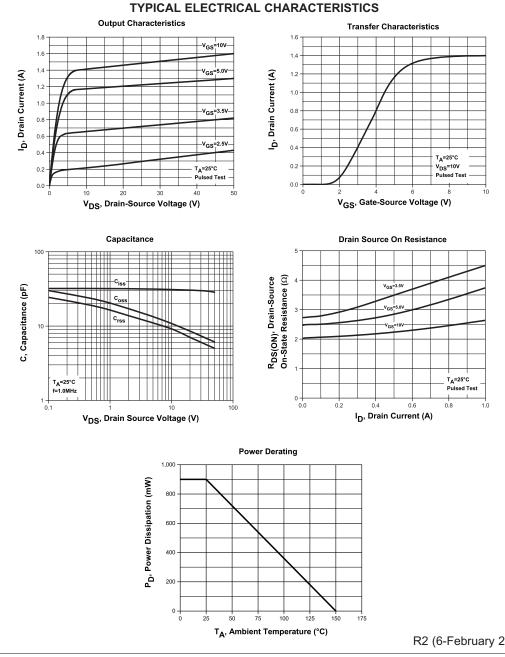
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CTLDM8002A-M621

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